



## Material Content Data Sheet



<b>Sales Product Name</b>				BSC070N10NS3 G		<b>Issued</b>		1. August 2018	
<b>MA#</b>				MA001617510					
<b>Package</b>				PG-TDSON-8-39		<b>Weight*</b>		113.83 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	3.666	3.22	3.22	32208	32208	
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		128		
	non noble metal	iron	7439-89-6	0.048	0.04		425		
	non noble metal	copper	7440-50-8	48.352	42.48	42.53	424770	425323	
	non noble metal	copper	7440-50-8	0.062	0.05	0.05	543	543	
wire	non noble metal	copper	7440-50-8	0.062	0.05	0.05	543	543	
encapsulation	organic material	carbon black	1333-86-4	0.079	0.07		696		
	plastics	epoxy resin	-	6.256	5.50		54957		
	inorganic material	silicondioxide	60676-86-0	33.259	29.22	34.79	292178	347831	
leadfinish	non noble metal	tin	7440-31-5	1.520	1.34	1.34	13353	13353	
plating	noble metal	silver	7440-22-4	0.158	0.14	0.14	1392	1392	
solder	non noble metal	tin	7440-31-5	0.061	0.05		533		
	noble metal	silver	7440-22-4	0.076	0.07		667		
	non noble metal	lead	7439-92-1	2.899	2.55	2.67	25471	26671	
heatspreader	inorganic material	phosphorus	7723-14-0	0.000	0.00		1		
	non noble metal	iron	7439-89-6	0.000	0.00		3		
	non noble metal	copper	7440-50-8	0.297	0.26	0.26	2610	2614	
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.005	0.00		45		
	non noble metal	iron	7439-89-6	0.017	0.01		149		
	noble metal	silver	7440-22-4	0.150	0.13		1318		
	non noble metal	copper	7440-50-8	16.910	14.86	15.00	148553	150065	
*deviation	< 10%			Sum in total:		100.00		1000000	

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com